

Marking Information (Cont.)

SMB



BXXXBE = Product Type Marking Code, ex: B120BE (SMB Package)

| | = Manufacturers' Code Marking

YWW = Date Code Marking

Y = Last Digit of Year (ex: 7 for 2017)

WW = Week Code (01 to 53)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	B120AE B120BE	B130AE B130BE	B140AE B140BE	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{RM}	20	30	40	V
Average Rectified Output Current	lo	1		Α	
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30		А	

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	SMA SMB	R _{θJA}	95 90	°C/W
Typical Thermal Resistance Junction to Case (Note 5)	SMA SMB	R _{eJC}	45 40	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

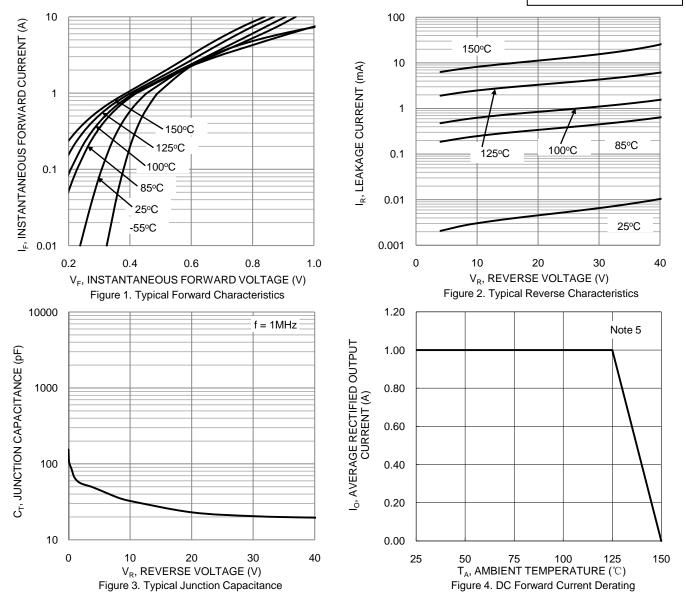
Characteri	stic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop		V _F	_	0.45 0.40	0.50 —	V	I _F = 1A, T _J = +25°C I _F = 1A, T _J = +125°C
Leakage Current (Note 6)	B120AE/B120BE B130AE/B130BE B140AE/B140BE	I _R	= = =	 6.1	0.1 0.1 0.2	mA	$V_R = 20V, T_J = +25$ °C $V_R = 30V, T_J = +25$ °C $V_R = 40V, T_J = +25$ °C $V_R = 40V, T_J = +125$ °C
Typical Capacitance		Ст	_	50		pF	$V_R = 4.0V, f = 1MHz$

Notes: 5. Device mounted on FR-4 substrate, 0.4" x 0.5", 2oz, single-sided, PC boards with 0.2" x 0.25" copper pad.

6. Short duration pulse test used to minimize self-heating effect.





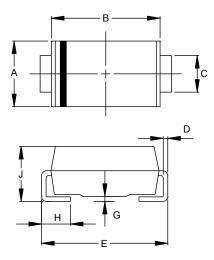




Package Outline Dimensions

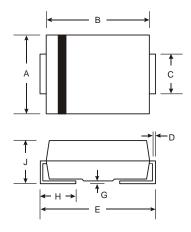
Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: SMA



SMA			
Dim	Min	Max	
Α	2.29	2.92	
В	4.00	4.60	
С	1.27	1.63	
D	0.15	0.31	
Е	4.80	5.59	
G	0.05	0.20	
Н	0.76	1.52	
J	1.96	2.40	
All Dimensions in mm			

(2) Package Type: SMB



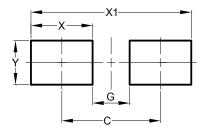
SMB			
Dim	Min	Max	
Α	3.30	3.94	
В	4.06	4.57	
C	1.96	2.21	
D	0.15	0.31	
Е	5.00	5.59	
G	0.05	0.20	
Н	0.76	1.52	
J	2.00	2.50	
All Dimensions in mm			



Suggested Pad Layout

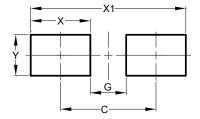
Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: SMA



Dimensions	Value (in mm)
С	4.00
G	1.50
Х	2.50
X1	6.50
Υ	1.70

(2) Package Type: SMB



Dimensions	Value (in mm)
С	4.30
G	1.80
Х	2.50
X1	6.80
Υ	2.30



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